



LG

website:<http://biz.LGservice.com>
e-mail:<http://www.LGEservice.com/techsup.html>

LCD TV **SERVICE MANUAL**

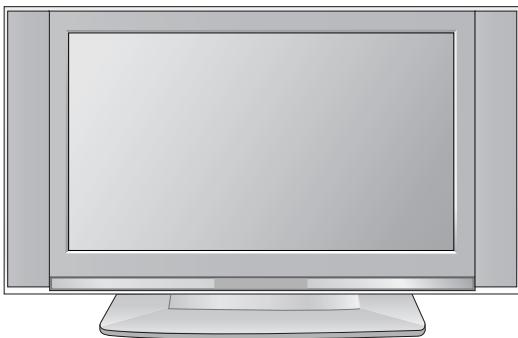
CHASSIS : ML-041B

FACTORY MODEL : 17LX1R-MB

MODEL : 17LX1R

CAUTION

BEFORE SERVICING THE CHASSIS,
READ THE SAFETY PRECAUTIONS IN THIS MANUAL.



CONTENTS

CONTENTS	2
PRODUCT SAFETY	3
SPECIFICATION	6
TIMING CHART	10
ADJUSTMENT INSTRUCTION.....	11
SVC REMOCON	12
TROUBLE SHOOTING	13
BLOCK DIAGRAM.....	18
WIRING DIAGRAM.....	20
EXPLODED VIEW	21
EXPLODED VIEW PARTS LIST	22
REPLACEMENT PARTS LIST	23
SVC. SHEET	

SAFETY PRECAUTIONS

IMPORTANT SAFETY NOTICE

Many electrical and mechanical parts in this chassis have special safety-related characteristics. These parts are identified by  in the Schematic Diagram and Replacement Parts List.

It is essential that these special safety parts should be replaced with the same components as recommended in this manual to prevent X-RADIATION, Shock, Fire, or other Hazards.

Do not modify the original design without permission of manufacturer.

General Guidance

An **isolation Transformer** should always be used during the servicing of a receiver whose chassis is not isolated from the AC power line. Use a transformer of adequate power rating as this protects the technician from accidents resulting in personal injury from electrical shocks.

It will also protect the receiver and its components from being damaged by accidental shorts of the circuitry that may be inadvertently introduced during the service operation.

If any fuse (or Fusible Resistor) in this TV receiver is blown, replace it with the specified.

When replacing a high wattage resistor (Oxide Metal Film Resistor, over 1W), keep the resistor 10mm away from PCB.

Keep wires away from high voltage or high temperature parts.

X-RAY Radiation

Warning:

The source of X-RAY RADIATION in this TV receiver is the High Voltage Section and the LCD PANEL.

For continued X-RAY RADIATION protection, the replacement panel must be the same type panel as specified in the Replacement Parts List.

To determine the presence of high voltage, use an accurate high impedance HV meter.

Adjust brightness, color, contrast controls to minimum.

Measure the high voltage.

The meter reading should indicate

$23.5 \pm 1.5\text{KV}$: 14-19 inch, $26 \pm 1.5\text{KV}$: 19-21 inch,

$29.0 \pm 1.5\text{KV}$: 25-29 inch, $30.0 \pm 1.5\text{KV}$: 32 inch

If the meter indication is out of tolerance, immediate service and correction is required to prevent the possibility of premature component failure.

Before returning the receiver to the customer,

always perform an **AC leakage current check** on the exposed metallic parts of the cabinet, such as antennas, terminals, etc., to be sure the set is safe to operate without damage of electrical shock.

Leakage Current Cold Check(Antenna Cold Check)

With the instrument AC plug removed from AC source, connect an electrical jumper across the two AC plug prongs. Place the AC switch in the on position, connect one lead of ohm-meter to the AC plug prongs tied together and touch other ohm-meter lead in turn to each exposed metallic parts such as antenna terminals, phone jacks, etc.

If the exposed metallic part has a return path to the chassis, the measured resistance should be between $1\text{M}\Omega$ and $5.2\text{M}\Omega$.

When the exposed metal has no return path to the chassis the reading must be infinite.

An other abnormality exists that must be corrected before the receiver is returned to the customer.

Leakage Current Hot Check (See below Figure)

Plug the AC cord directly into the AC outlet.

Do not use a line Isolation Transformer during this check.

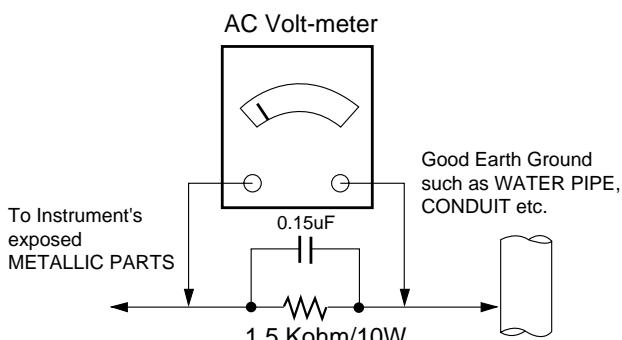
Connect $1.5\text{K}/10\text{watt}$ resistor in parallel with a $0.15\mu\text{F}$ capacitor between a known good earth ground (Water Pipe, Conduit, etc.) and the exposed metallic parts.

Measure the AC voltage across the resistor using AC voltmeter with 1000 ohms/volt or more sensitivity.

Reverse plug the AC cord into the AC outlet and repeat AC voltage measurements for each exposed metallic part. Any voltage measured must not exceed 0.75 volt RMS which corresponds to 0.5mA.

In case any measurement is out of the limits specified, there is possibility of shock hazard and the set must be checked and repaired before it is returned to the customer.

Leakage Current Hot Check circuit



SERVICING PRECAUTIONS

CAUTION: Before servicing receivers covered by this service manual and its supplements and addenda, read and follow the **SAFETY PRECAUTIONS** on page 3 of this publication.

NOTE: If unforeseen circumstances create conflict between the following servicing precautions and any of the safety precautions on page 3 of this publication, always follow the safety precautions. Remember: Safety First.

General Servicing Precautions

1. Always unplug the receiver AC power cord from the AC power source before;
 - a. Removing or reinstalling any component, circuit board module or any other receiver assembly.
 - b. Disconnecting or reconnecting any receiver electrical plug or other electrical connection.
 - c. Connecting a test substitute in parallel with an electrolytic capacitor in the receiver.

CAUTION: A wrong part substitution or incorrect polarity installation of electrolytic capacitors may result in an explosion hazard.

2. Test high voltage only by measuring it with an appropriate high voltage meter or other voltage measuring device (DVM, FETVOM, etc) equipped with a suitable high voltage probe. Do not test high voltage by "drawing an arc".

3. Do not spray chemicals on or near this receiver or any of its assemblies.

4. Unless specified otherwise in this service manual, clean electrical contacts only by applying the following mixture to the contacts with a pipe cleaner, cotton-tipped stick or comparable non-abrasive applicator; 10% (by volume) Acetone and 90% (by volume) isopropyl alcohol (90%-99% strength)

CAUTION: This is a flammable mixture.

Unless specified otherwise in this service manual, lubrication of contacts is not required.

5. Do not defeat any plug/socket B+ voltage interlocks with which receivers covered by this service manual might be equipped.

6. Do not apply AC power to this instrument and/or any of its electrical assemblies unless all solid-state device heat sinks are correctly installed.

7. Always connect the test receiver ground lead to the receiver chassis ground before connecting the test receiver positive lead.

Always remove the test receiver ground lead last.

8. *Use with this receiver only the test fixtures specified in this service manual.*

CAUTION: Do not connect the test fixture ground strap to any heat sink in this receiver.

Electrostatically Sensitive (ES) Devices

Some semiconductor (solid-state) devices can be damaged easily by static electricity. Such components commonly are called

Electrostatically Sensitive (ES) Devices. Examples of typical ES devices are integrated circuits and some field-effect transistors and semiconductor "chip" components. The following techniques should be used to help reduce the incidence of component damage caused by static by static electricity.

1. Immediately before handling any semiconductor component or semiconductor-equipped assembly, drain off any electrostatic charge on your body by touching a known earth ground. Alternatively, obtain and wear a commercially available discharging wrist strap device, which should be removed to prevent potential shock reasons prior to applying power to the

unit under test.

2. After removing an electrical assembly equipped with ES devices, place the assembly on a conductive surface such as aluminum foil, to prevent electrostatic charge buildup or exposure of the assembly.
3. Use only a grounded-tip soldering iron to solder or unsolder ES devices.
4. Use only an anti-static type solder removal device. Some solder removal devices not classified as "anti-static" can generate electrical charges sufficient to damage ES devices.
5. Do not use freon-propelled chemicals. These can generate electrical charges sufficient to damage ES devices.
6. Do not remove a replacement ES device from its protective package until immediately before you are ready to install it. (Most replacement ES devices are packaged with leads electrically shorted together by conductive foam, aluminum foil or comparable conductive material).
7. Immediately before removing the protective material from the leads of a replacement ES device, touch the protective material to the chassis or circuit assembly into which the device will be installed.

CAUTION: Be sure no power is applied to the chassis or circuit, and observe all other safety precautions.

8. Minimize bodily motions when handling unpackaged replacement ES devices. (Otherwise harmless motion such as the brushing together of your clothes fabric or the lifting of your foot from a carpeted floor can generate static electricity sufficient to damage an ES device.)

General Soldering Guidelines

1. Use a grounded-tip, low-wattage soldering iron and appropriate tip size and shape that will maintain tip temperature within the range of 500 °F to 600 °F.

2. Use an appropriate gauge of RMA resin-core solder composed of 60 parts tin/40 parts lead.

3. Keep the soldering iron tip clean and well tinned.

4. Thoroughly clean the surfaces to be soldered. Use a small wire-bristle (0.5 inch, or 1.25cm) brush with a metal handle. Do not use freon-propelled spray-on cleaners.

5. Use the following unsoldering technique

- a. Allow the soldering iron tip to reach normal temperature. (500 °F to 600 °F)

- b. Heat the component lead until the solder melts.

- c. Quickly draw the melted solder with an anti-static, suction-type solder removal device or with solder braid.

CAUTION: Work quickly to avoid overheating the circuitboard printed foil.

6. Use the following soldering technique.

- a. Allow the soldering iron tip to reach a normal temperature (500 °F to 600 °F)

- b. First, hold the soldering iron tip and solder the strand against the component lead until the solder melts.

- c. Quickly move the soldering iron tip to the junction of the component lead and the printed circuit foil, and hold it there only until the solder flows onto and around both the component lead and the foil.

CAUTION: Work quickly to avoid overheating the circuit board printed foil.

- d. Closely inspect the solder area and remove any excess or splashed solder with a small wire-bristle brush.

IC Remove/Replacement

Some chassis circuit boards have slotted holes (oblong) through which the IC leads are inserted and then bent flat against the circuit foil. When holes are the slotted type, the following technique should be used to remove and replace the IC. When working with boards using the familiar round hole, use the standard technique as outlined in paragraphs 5 and 6 above.

Removal

1. Desolder and straighten each IC lead in one operation by gently prying up on the lead with the soldering iron tip as the solder melts.
2. Draw away the melted solder with an anti-static suction-type solder removal device (or with solder braid) before removing the IC.

Replacement

1. Carefully insert the replacement IC in the circuit board.
2. Carefully bend each IC lead against the circuit foil pad and solder it.
3. Clean the soldered areas with a small wire-bristle brush.
(It is not necessary to reapply acrylic coating to the areas).

"Small-Signal" Discrete Transistor

Removal/Replacement

1. Remove the defective transistor by clipping its leads as close as possible to the component body.
2. Bend into a "U" shape the end of each of three leads remaining on the circuit board.
3. Bend into a "U" shape the replacement transistor leads.
4. Connect the replacement transistor leads to the corresponding leads extending from the circuit board and crimp the "U" with long nose pliers to insure metal to metal contact then solder each connection.

Power Output, Transistor Device

Removal/Replacement

1. Heat and remove all solder from around the transistor leads.
2. Remove the heat sink mounting screw (if so equipped).
3. Carefully remove the transistor from the heat sink of the circuit board.
4. Insert new transistor in the circuit board.
5. Solder each transistor lead, and clip off excess lead.
6. Replace heat sink.

Diode Removal/Replacement

1. Remove defective diode by clipping its leads as close as possible to diode body.
2. Bend the two remaining leads perpendicular y to the circuit board.
3. Observing diode polarity, wrap each lead of the new diode around the corresponding lead on the circuit board.
4. Securely crimp each connection and solder it.
5. Inspect (on the circuit board copper side) the solder joints of the two "original" leads. If they are not shiny, reheat them and if necessary, apply additional solder.

Fuse and Conventional Resistor

Removal/Replacement

1. Clip each fuse or resistor lead at top of the circuit board hollow stake.
2. Securely crimp the leads of replacement component around notch at stake top.
3. Solder the connections.

CAUTION: Maintain original spacing between the replaced component and adjacent components and the circuit board to prevent excessive component temperatures.

Circuit Board Foil Repair

Excessive heat applied to the copper foil of any printed circuit board will weaken the adhesive that bonds the foil to the circuit board causing the foil to separate from or "lift-off" the board. The following guidelines and procedures should be followed whenever this condition is encountered.

At IC Connections

To repair a defective copper pattern at IC connections use the following procedure to install a jumper wire on the copper pattern side of the circuit board. (Use this technique only on IC connections).

1. Carefully remove the damaged copper pattern with a sharp knife. (Remove only as much copper as absolutely necessary).
2. carefully scratch away the solder resist and acrylic coating (if used) from the end of the remaining copper pattern.
3. Bend a small "U" in one end of a small gauge jumper wire and carefully crimp it around the IC pin. Solder the IC connection.
4. Route the jumper wire along the path of the out-away copper pattern and let it overlap the previously scraped end of the good copper pattern. Solder the overlapped area and clip off any excess jumper wire.

At Other Connections

Use the following technique to repair the defective copper pattern at connections other than IC Pins. This technique involves the installation of a jumper wire on the component side of the circuit board.

1. Remove the defective copper pattern with a sharp knife. Remove at least 1/4 inch of copper, to ensure that a hazardous condition will not exist if the jumper wire opens.
2. Trace along the copper pattern from both sides of the pattern break and locate the nearest component that is directly connected to the affected copper pattern.
3. Connect insulated 20-gauge jumper wire from the lead of the nearest component on one side of the pattern break to the lead of the nearest component on the other side.
Carefully crimp and solder the connections.

CAUTION: Be sure the insulated jumper wire is dressed so the it does not touch components or sharp edges.

SPECIFICATION

NOTE : Specifications and others are subject to change without notice for improvement.

1. Application range

This specification is applied to ML-041B chassis.

2. Requirement for Test

Testing for standard of each part must be followed in below condition.

- (1) Temperature : $25^{\circ}\text{C} \pm 2^{\circ}\text{C}$
- (2) Humidity : $65\% \pm 10\%$
- (3) Power : Standard input voltage (AC 100-240V, 50/60Hz)
- (4) Measurement must be performed after heat-run more than 30min.
- (5) Adjusting standard for this chassis is followed a special standard.

3. General Specification

No.	Item	Specification	Remark
1	Maker	LPL	LPL
	Type	TFT Color LCD Module	
	ActiveDisplay Area	17.0 inches(434.38mm) diagonal	
	Pixel Pitch [mm]	0.291mm(H)x0.291mm(V)xRGB	
	Electrical Interface	LVDS	
	Color Depth	6BIT, 16,777,216 colors	
	Size [mm]	400(H) x 258.7(V) x 22(D)	
	Surface Treatment	Anti Glare Hard Coating	
	Operating Mode	Normally Black	
	Back light Unit	4 CCFL(4 lamps)	
	R/T Typ.	R.T.:12ms + F.T.:13ms	

*Function

No	Item	Specification	Remark
1	Teletext	TOP, FLOF, LIST 10 page	Top(option) / ONLY PAL
2	REMOCON	NEC Code	PAL/ NTSC
3	AV Input	2	Rear(option, NT), side(ONLY 50tool)
4	S-Vedio Input	1	Rear
5	Component input	1	Rear (option, NT) Except COMMERCIAL
6	PERI TV Connector	Full SCART : 1	Rear (option, EU)
7	RGB(VGA)Input	1	D-sub 15 pin
8	H/p input	1	
9	PC Sound input	1	Except COMMERCIAL
10	RS-232	YES	ONLY COMMERCIAL
11	Discrete IR	YES	ONLY COMMERCIAL
12	2 Carrier Stereo	BG, DK	ONLY PAL
13	NICAM Stereo	BG, I, LL'	ONLY PAL
14	2 Carrier Dual	BG, DK	ONLY PAL
15	NICAM Dual	BG, I, LL'	ONLY PAL
16	DW(Double Window) Mode	X	
17	MW(Multi Window) Mode	X	
18	Film Mode	X	
19	Noise Reduction	X	
20	Progressive Scan	0	
21	Motion Detection	X	
22	SRS WOW	X	
23	wivel Speaker	X	
24	Ez-pip	X	
25	ARC	0	
26	DRP	0	
27	DCDI	X	
28	HDCP	X	
29	LIGHTING LOGO	0	ONLY 17LX1R

4. Mechanical specification

No	Item		Content			Remark
1	Product Dimension		Width (W)	Length (D)	Height (H)	
		Before Packing	553.5	181	365.7	With SPK, Stand
		After Packing	577	280	490	
2	Product Weight	Only SET	7.7kg			
		With BOX	9.8 kg			

5.Engineering Specification

5-1.General Specification(TV)

No.	ITEM	CONTENTS			REMARK
	ENERGE	SYNC(V/H)	VIDEO	POWER CONSUMPTION	LED COLOR
1	Normal	On/On	Active	≤65W	Green
	Stand By,	Off/On		≤1W(110 V) ≤2W	Red
	Cut-off Switch off	-	-	0W	OFF
				PBP SWAP ► ON/OFF	
	ITEM	Specification			Remark
2	D-SUB Pin configuration	1 : RED 3 : Blue 5 : S.T (GND) 7 : Green GND 9 : N.C 11: ID0(GND) 13: H-Sync 15: SCL	2 : Green 4 : ID2 (GND) 6 : RED GND 8 : Blue GND 10: D-GND 12:SDA 14: V-Sync Shell: GND		10: Digital GND
3	Control Function	1) Contrast/Brightness 2) H-Position / V-Position 3) Tracking : Clock / Phase 4) Auto Configure RESET			
4	Comoponent Jack	1 : Y 3 : Pb 5 : Pr			Middle east / NTSC Area
5	D4 Jack (525i,525p,750p,1125i)	1 : Y 3 : Pb 5 : Pr 7 : Line1 Ready 9 : LINE2 11: LINE3 13: Line3 Ready	2 : Y GND 4 : Pb GND 6 : Pr GND 8 : LINE1 10:Line2 Ready 12:SWITCH GND 14: SWITCH		JAPAN Only

6. Signal Timing(Resolution)

6-1. PC Mode

[Table 7] Timming chart of Receivable Mode

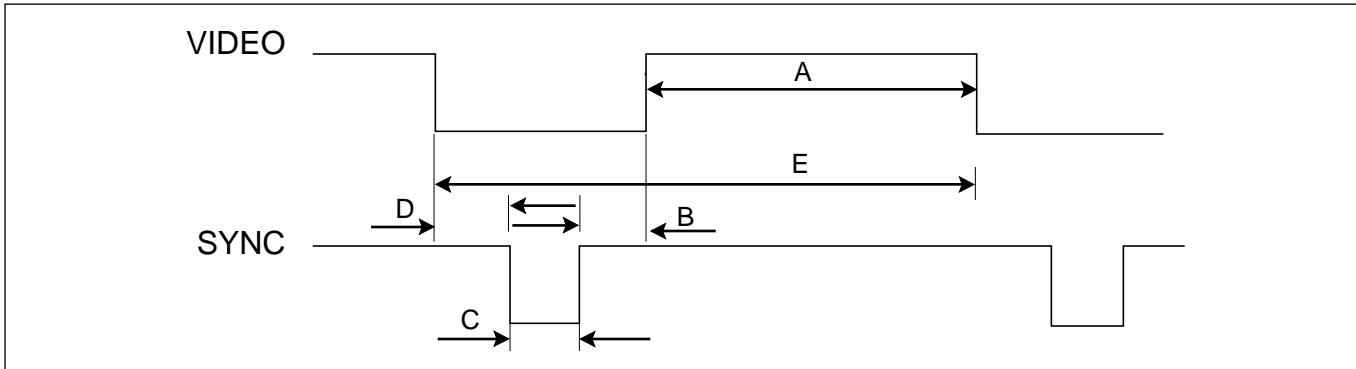
* H [dot] / V [line]

Mode	VGA-60	VGA-67	VGA-75	SVGA-56	SVGA-60	SVGA-72	SVGA-75	XGA-60	XGA-70	XGA-75	WXGA-60
H_display	640	640	640	800	800	800	800	1024	1024	1024	1280
V_display	480	480	480	600	600	600	600	768	768	768	768
V frequency	60	67	75	56	60	72	75	60	70	75	60
H_total	800	864	840	1024	1056	1040	1056	1344	1328	1312	1680
H_blankning	160	224	200	224	256	240	256	320	304	288	400
H_sync	96	64	64	72	128	120	80	136	136	96	136
H Polarity	NEG.	NEG.	NEG	POS	POS	POS	POS	NEG	NEG	POS	NEG
H_bp	48	96	120	128	88	64	160	136	144	176	200
H_fp	16	64	16	24	40	56	16	160	24	16	64
H-freq[kHz]	31.469	35.0	37.5	35.156	37.879	48.077	46.875	48.363	56.476	60.023	47.693
/Clk[MHz]	25.175	30.24	31.5	36.0	40.0	50.0	49.5	65.0	75.0	78.75	80.125
V_total	525	525	500	625	628	666	625	806	806	800	795
V_blankning	45	45	20	25	28	66	25	38	38	32	27
V_sync	2	3	3	2	4	6	3	6	6	3	7
V Polarity	NEG	NEG	NEG	POS	POS	POS	POS	NEG	NEG	POS	POS
V_bp	33	39	16	22	23	23	21	29	29	28	19
V_fp	10	3	1	1	1	37	1	3	3	1	1

7. Optical Character

No	Item	Specification				Remark
				LPL		
1	Viewing Angle <CR ≥ 10>	R/L		88/88		
		U/D		88/88		
2	Luminance	Luminance (cd/m2)		450		Typical
		Variation		1.3		MAX
3	Contrast Ratio			400		All white / All black
4	CIE Color Coordinates	White	WX	Typ.	0.289	Min = Typ. - 0.03 Max = Typ. + 0.03
			WY	Typ.	0.303	
		RED	Xr	Typ.	0.633	
			Yr	Typ.	0.341	
		Green	Xg	Typ.	0.280	
			Yg	Typ.	0.069	
		Blue	Xb	Typ.	0.145	
			Yb	Typ.	0.069	

TIMING CHART



<< Dot Clock (**MHz**), Horizontal Frequency (**kHz**), Vertical Frequency (**Hz**), Horizontal etc... (**μs**), Vertical etc... (**ms**) >>

Mode	H/V Sort	Sync Polarity	Dot Clock	Frequency	Total Period (E)	Video Active Time (A)	Front Porch (B)	Sync Duration (D)	Back Porch (F)	Resolution
1	H	+	25.175	31.469	800	640	16	96	48	640x480
	V	-		59.94	525	480	10	2	33	
2	H	-	30.240	35	864	640	64	64	96	640x480
	V	+		66.667	525	480	3	3	39	
3	H	-	31.5	37.5	840	640	16	64	120	640x480
	V	-		75	500	480	1	3	16	
4	H	-	36	35.156	1024	800	24	72	128	800x600
	V	-		56.25	625	600	1	2	22	
5	H	+	40.0	37.879	1056	800	40	128	88	800x600
	V	+		60.317	628	600	1	4	23	
6	H	+	50.0	48.077	1040	800	56	120	64	800x600
	V	+		72.188	666	600	37	6	23	
7	H	+/-	49.5	46.875	1056	800	16	80	160	800x600
	V	+/-		75.0	625	600	1	3	21	
8	H	-	65.0	48.363	1344	1024	24	136	160	1024x768
	V	-		60.004	806	768	3	6	29	
9	H	+	75	56.476	1328	1024	24	136	144	1024x768
	V	+		70.069	806	768	3	6	29	
10	H	+	78.75	60.023	1312	1024	16	96	176	1280x768
	V	-		75.029	800	768	1	3	28	
11	H	+	79.50	47.776	1664	1280	64	128	192	1280x768
	V	-		59.870	798	768	3	7	20	

ADJUSTMENT INSTRUCTION

1. Application

This document is applied to 17" Wide LCD TV which is manufactured in Monitor Factory or is produced on the basis of this data.

2. Adjustment

2.1 Adjustment Details

The machine can be adjusted by itself automatically but even for self -adjustment it needs someone to operate it.

2.2 Auto Gain/Offset adjustment

2.2.1 RF Mode adjustment

2.2.1.1 Adjustment preparation

- Execution of RF no signal during Heat Run over 30min.

2.2.1.2 Auto Gain/Offset adjustment

- Press IN-START Key by using the Remote Controller (SVC), after converting to Adjustment-Mode,Press VOL+ Key consecutively in Scaler Auto gain menu. (RM-17LZ40/50/17LX1R press INSTART key two times)
- After adjustment is complete, pressing enter key, stores and completes the process.

2.2.2 Component Mode adjustment

(Model: Only RT/RM-17LZ40/50/17LX1R which is possible to input Component signal)

2.2.2.1 Adjustment preparation

- Execution of RF no signal during Heat Run over 30min.
- The component jack(Y,Pb,Pr) of LCD TV is connected to Y, Pb, Pr Output Signal of Pattern Generator (MSPG-925 SERISE)

2.2.2.2 Auto Gain/Offset adjustment

- Convert to Component Mode in Input-Mode.
- Select MODEL : 228 (480p Mode, Y : 100%, Pb/Pr : 75%) in Pattern Generator

Select PATTERN : 33 (Color Bar Pattern signal) in Pattern Generator

(MSPG-925 SERISE)

- Press IN-START Key by using the Remote Controller(SVC) , after converting to Adjustment-Mode, press VOL+ Key consecutively in AutoGain Menu.
- After adjustment is complete, pressing enter key, stores and completes the process.

2.2.3 PC Mode adjustment

2.2.3.1 Adjustment preparation

- Execution of RF no signal during Heat Run over 30min.
- 15 Pin D-Sub Jack of LCD TV is connected to the signal of Pattern Generator.

2.2.3.2 Auto Gain/Offset adjustment

- Convert to PC Mode in Input-Mode.
- mpress Resolution XGA (1024X768) and Pattern 16 Step Gray Signal ,or 16 Step (11 Step) Gray Signal which follows in the VG819.
- Press IN-START Key by using the Remote Controller(SVC) , after converting to Adjustment-Mode, press VOL+ Key consecutively in AutoGain Menu.
- After adjustment is complete, pressing enter key, stores and completes the process

2.3 EDID (The Extended Display Identification Data) Adjustment

- Connect 15 Pin D-Sub Cable to D-Sub Jac.
- Set up the input mode of the SET to PC
- For the DDC connect an automation equipment and data is written on DDC.

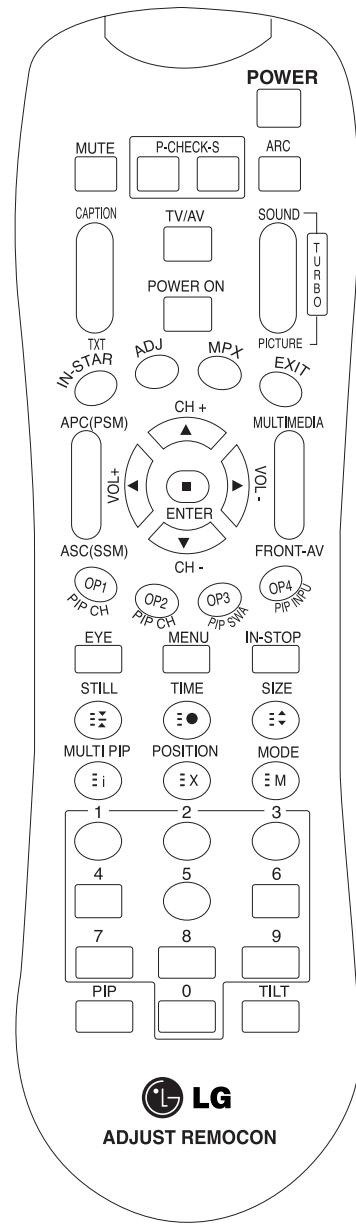
(Refer to Working Order for relative setting up)

2.3.1 EDID DATA

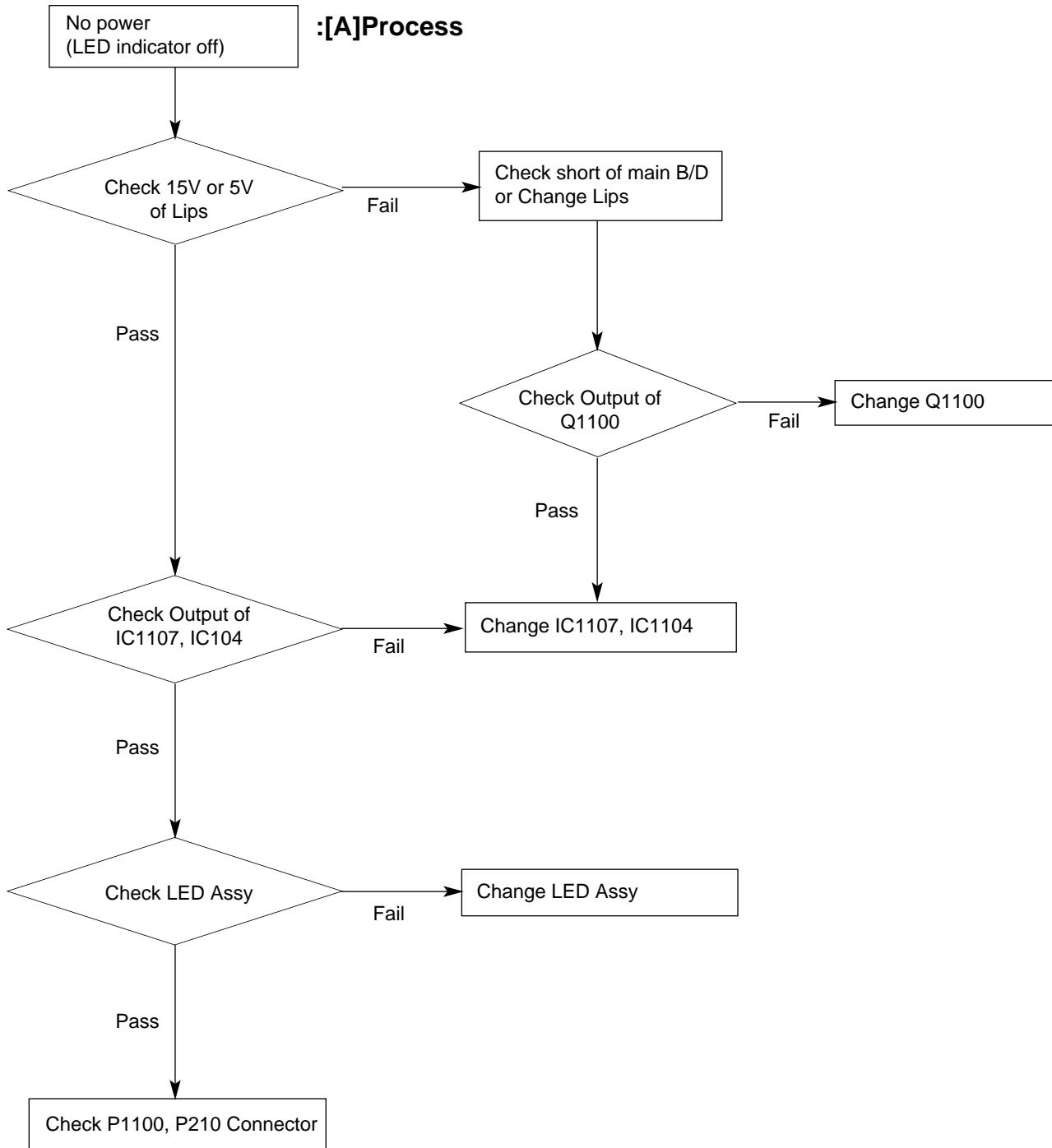
00	01	02	03	04	05	06	07	08	09	0A	0B	0C	0D	0E	0F
00	00	FF	FF	FF	FF	FF	00	1E	6D	F9	43	01	01	01	01
10	04	0F	01	01	20	39	21	78	EE	1D	32	A2	57	47	9A
20	11	4A	4D	A5	CE	00	61	4F	45	4A	31	4F	01	01	01
30	01	01	01	01	01	01	0E	1F	00	80	51	00	1E	30	40
40	37	00	74	DF	10	00	00	1E	00	00	00	FD	00	38	4B
50	41	09	00	0A	20	20	20	20	20	00	00	00	FC	00	31
60	37	4C	58	31	52	0A	20	20	20	20	20	20	00	00	FC
70	00	0A	20	20	20	20	20	20	20	20	20	20	20	00	C2

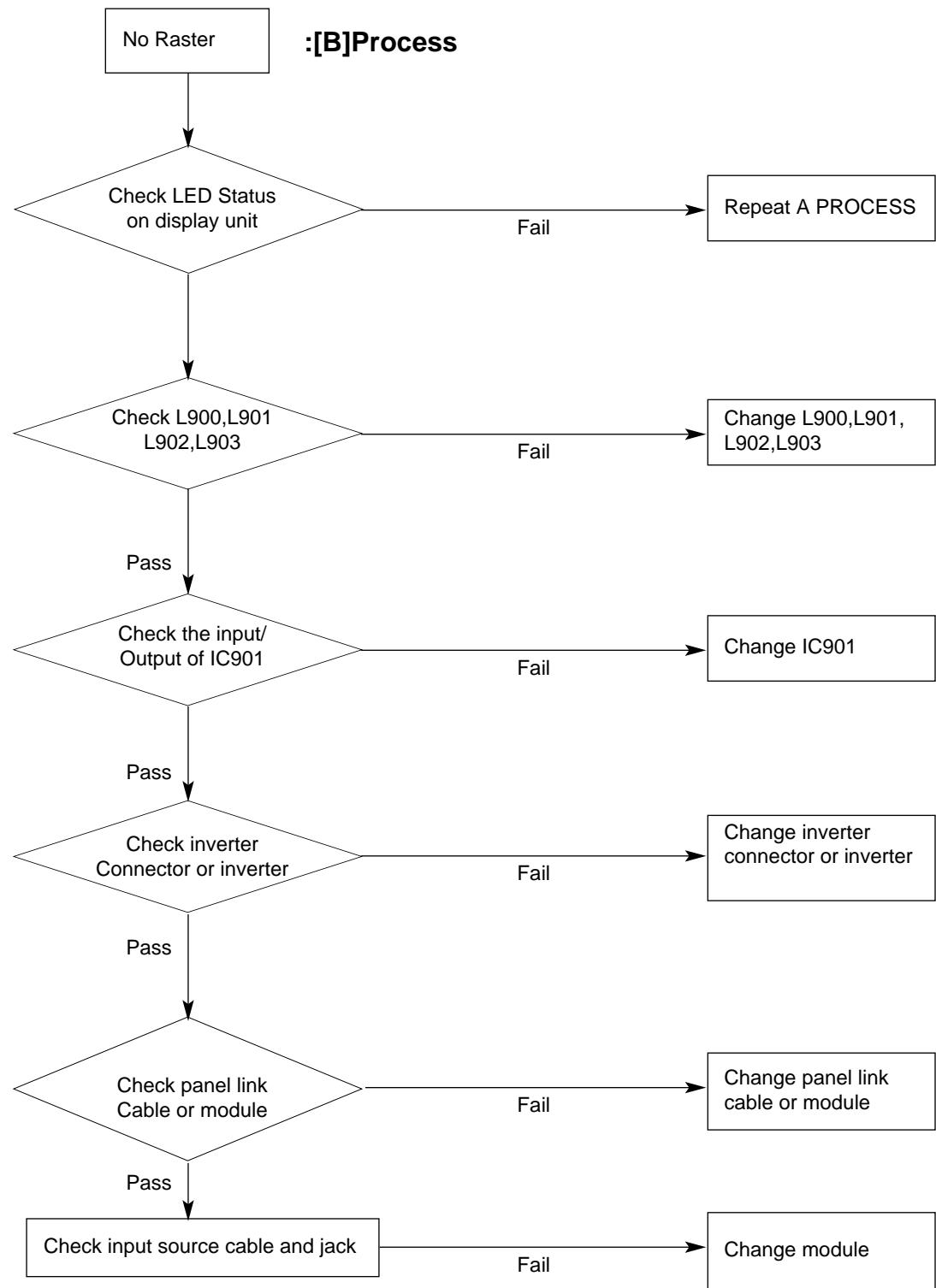
SVC REMOCON

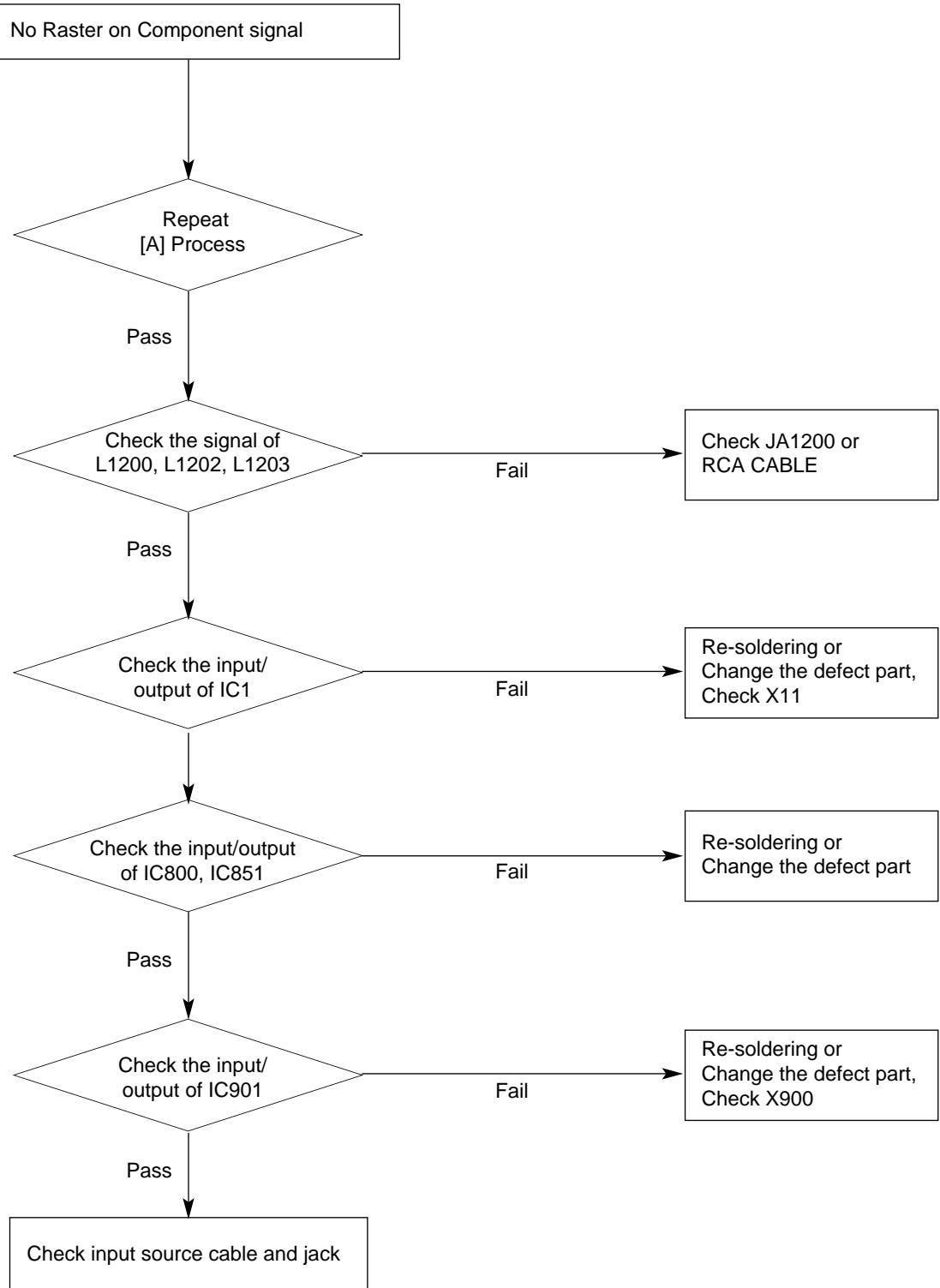
NO	KEY	FUNTION	REMARK
1	POWER	To turn the TV on or off	
2	POWER ON	To turn the TV on automatically if the power is supplied to the TV. (Use the POWER key to deactivate): It should be deactivated when delivered.	
3	MUTE	To activate the mute function.	
4	P-CHECK	To check TV screen image easily.	Shortcut keys
5	S-CHECK	To check TV screen sound easily	Shortcut keys
6	ARC	To select size of the main screen (Normal, Spectacle, Wide or Zoom)	Shortcut keys
7	CAPTION	Switch to closed caption broadcasting	
8	TXT	To toggle on/off the teletext mode	
9	TV/AV	To select an external input for the TV screen	
10	TURBO SOUND	To start turbo sound	
11	TURBO PICTURE	To start turbo picture	
12	IN-START	To enter adjustment mode when manufacturing the TV sets. To adjust the screen voltage (automatic): In-start → mute → Adjust → AV(Enter into W/B adjustment mode) W/B adjustment (automatic): After adjusting the screen → W/B adjustment → Exit two times (Adjustment completed)	Use the AV key to enter the screen W/B adjustment mode.
13	ADJ	To enter into the adjustment mode. To adjust horizontal line and sub-brightness.	
14	MPX	To select the multiple sound mode (Mono, Stereo or Foreign language)	
15	EXIT	To release the adjustment mode	
16	APC(PSM)	To easily adjust the screen according to surrounding brightness	
17	ASC(SSM)	To easily adjust sound according to the program type	
18	MULTIMIDIA	To check component input	Shortcut keys
19	FRONT-AV	To check the front AV	Shortcut keys
20	CH±	To move channel up/down or to select a function displayed on the screen.	
21	VOL±	To adjust the volume or accurately control a specific function.	
22	ENTER	To set a specific function or complete setting.	
23	PIP CH-(OP1)	To move the channel down in the PIP screen. To use as a red key in the teletext mode	
24	PIP CH+(OP2)	To move the channel in the PIP screen To use as a green key in the teletext mode	
25	PIP SWAP(OP3)	To switch between the main and sub screens To use as a yellow key in the teletext mode	
26	PIP INPUT(OP4)	To select the input status in the PIP screen To use as a blue key in the teletext mode	
27	EYE	To set a function that will automatically adjust screen status to match the surrounding brightness so natural color can be displayed.	
28	MENU	To select the functions such as video, voice, function or channel.	
29	IN-STOP	To set the delivery condition status after manufacturing the TV set.	
30	STILL	To halt the main screen in the normal mode, or the sub screen at the PIP screen. Used as a hold key in the teletext mode (Page updating is stopped.)	
31	TIME	Displays the teletext time in the normal mode Enables to select the sub code in the teletext mode	
32	SIZE	Used as the size key in the PIP screen in the normal mode Used as the size key in the teletext mode	
33	MULTI PIP	Used as the index key in the teletext mode (Top index will be displayed if it is the top text.)	
34	POSITION	To select the position of the PIP screen in the normal mode Used as the update key in the teletext mode (Text will be displayed if the current page is updated.)	
35	MODE	Used as Mode in the teletext mode	
36	PIP	To select the simultaneous screen	
37	TILT	To adjust screen tilt	Shortcut keys
38	0~9	To manually select the channel.	

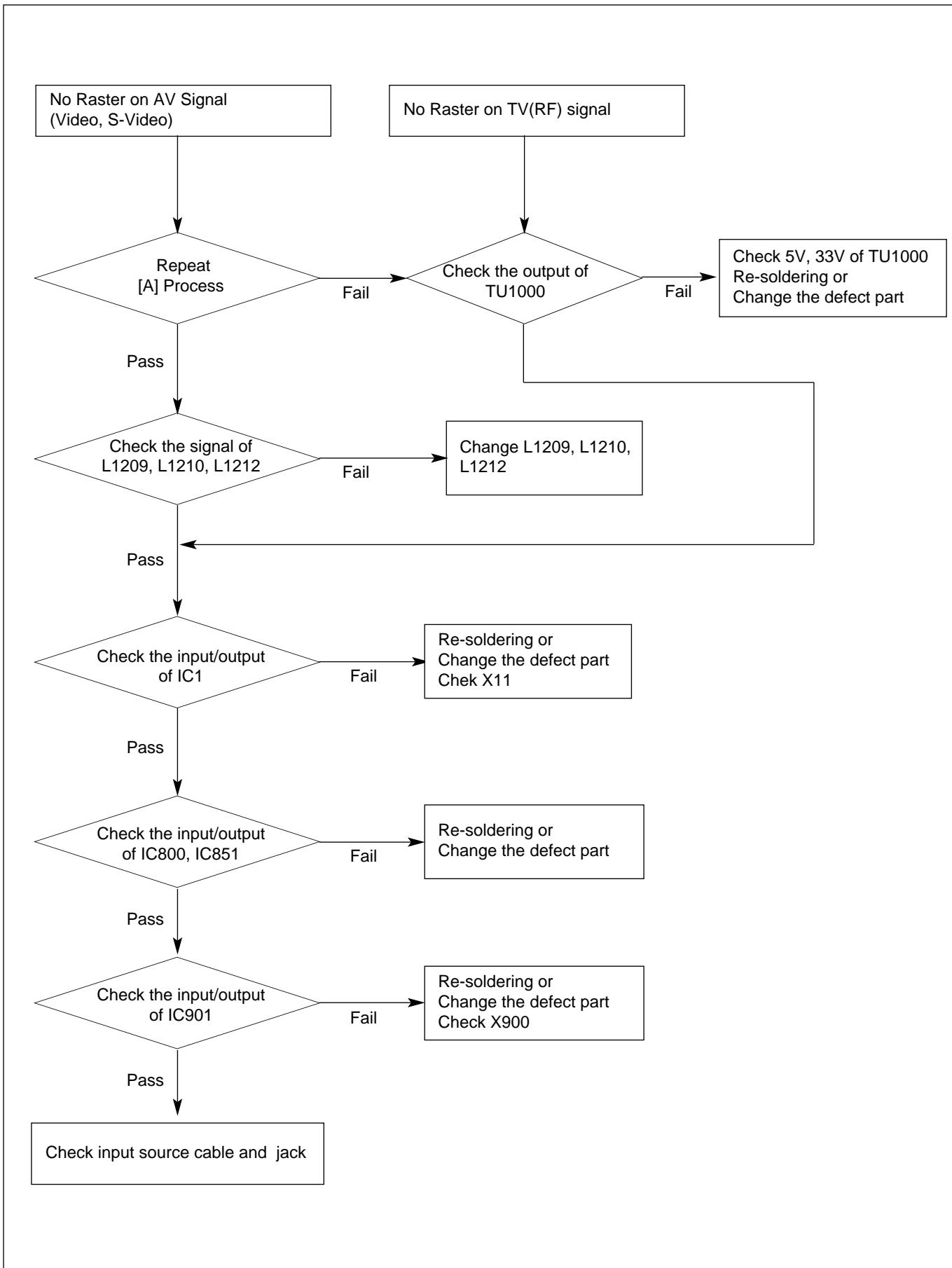


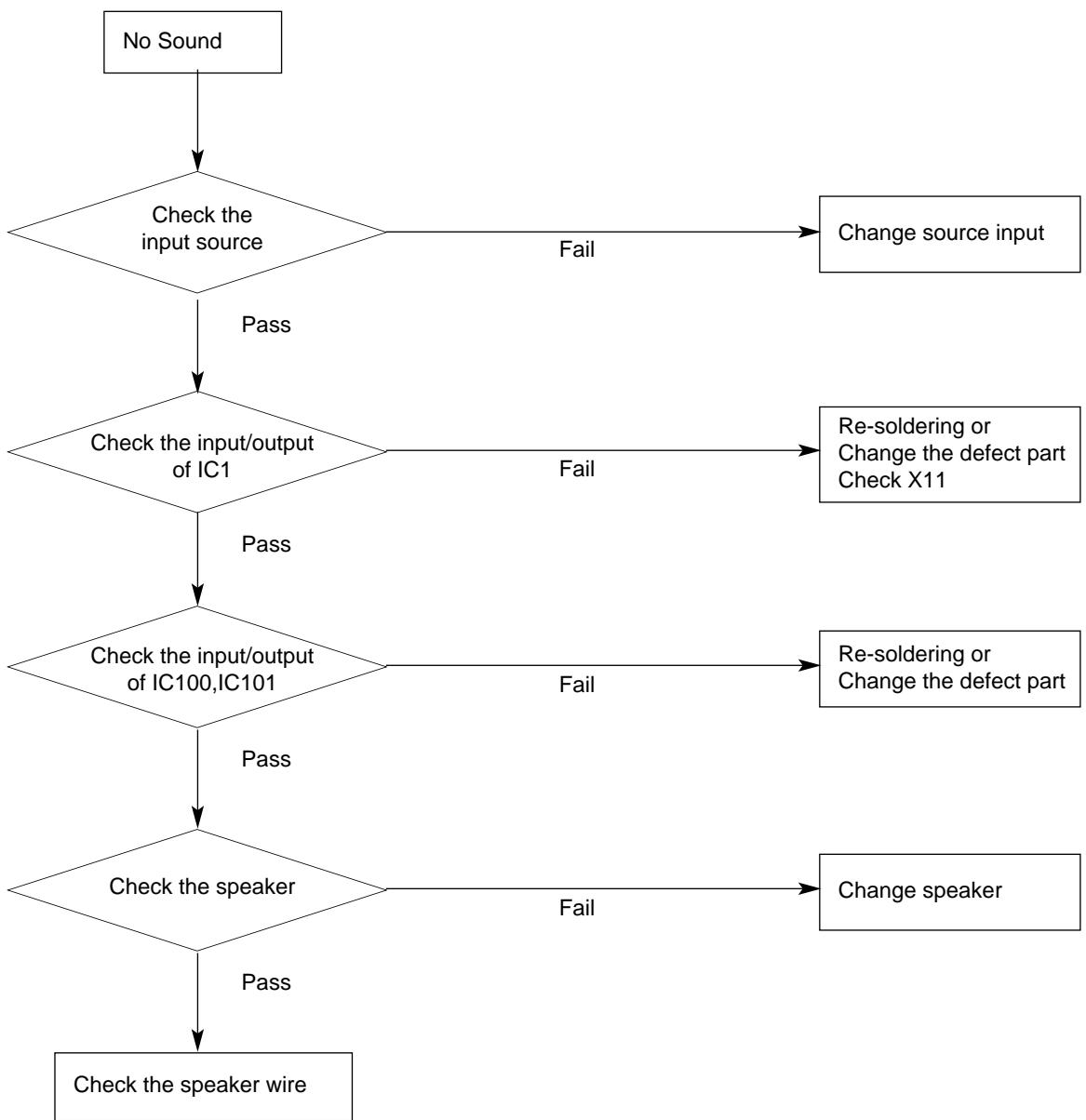
TROUBLESHOOTING



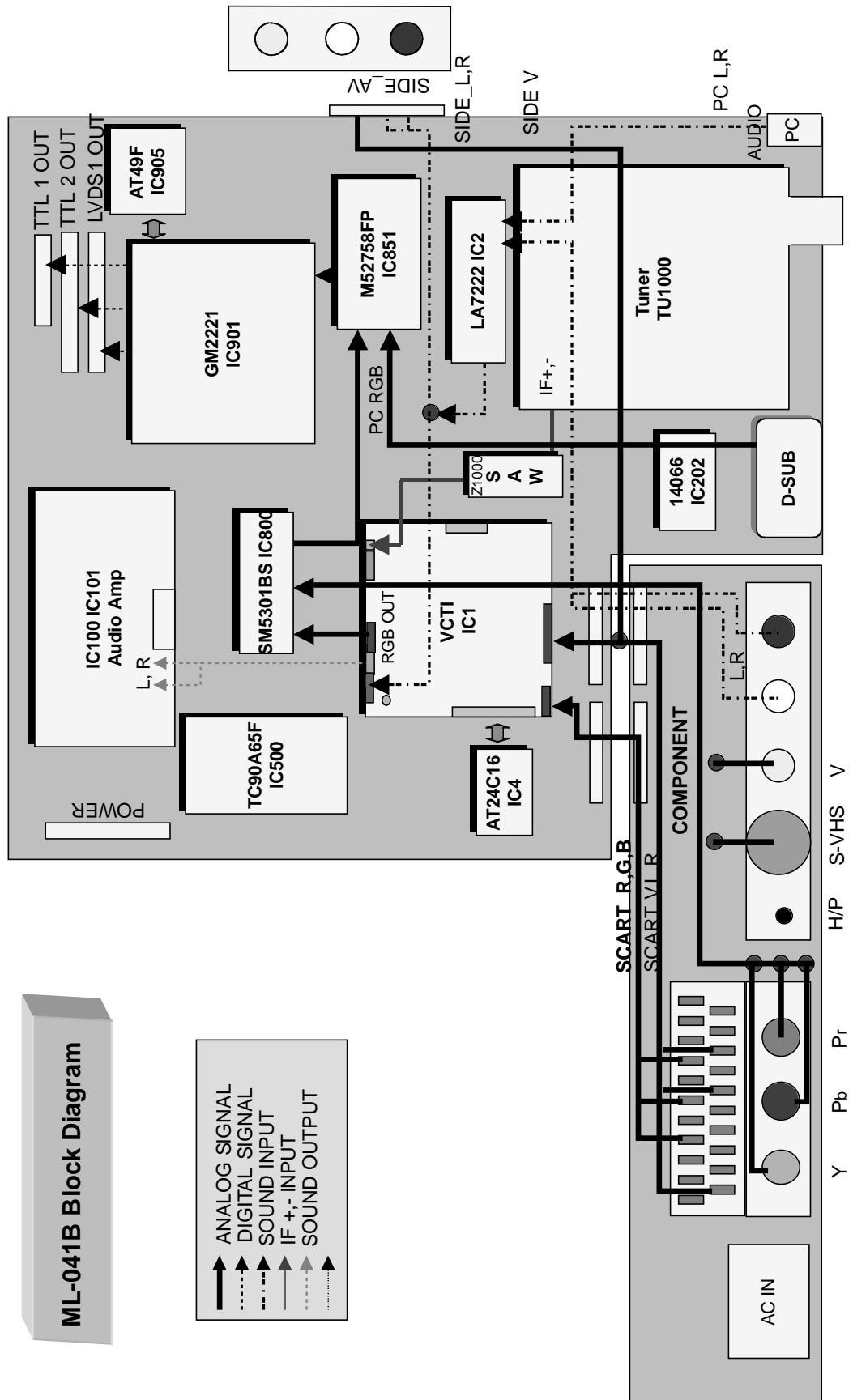








BLOCK DIAGRAM



BLOCK DIAGRAM DESCRIPTION

1. Video Controller Unit & Display Data Conversion Unit

The video controller unit receives the video signals inputted through the tuner, AV port (AV1, AV2, S-Video, component), and converts them into an analog RGB signal through the microcomputer (VCTI) combined with the video decoder that integrates various functions in one chip.

Either the analog RGB, component YPbPr or PC RGB signal is selected by the switching IC and inputted to a scaler (GM2221), which is sent to the LCD module after being modified to an LVDS signal through the integrated LVDS IC.

Or, it is sent to the LCD module as a TTL output.

VCTi is the main microprocessor that handles video signal processing and sound signal processing. It also manages the RF signals received from the tuner.

The scaler can control timing to fit into the LCD panel, and can also control the size and position of the input signal.

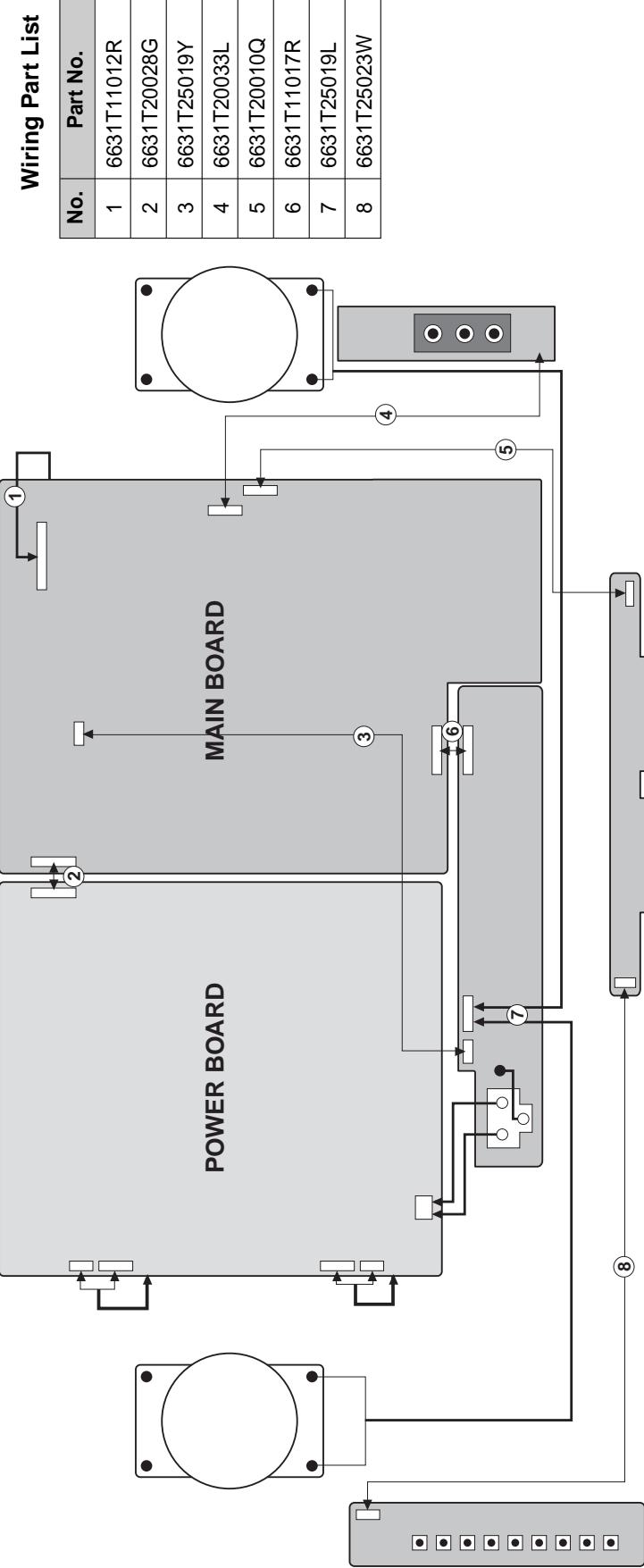
2. Power Supply Unit

The power supply unit provides 15V and 5V DC power to the mainboard.

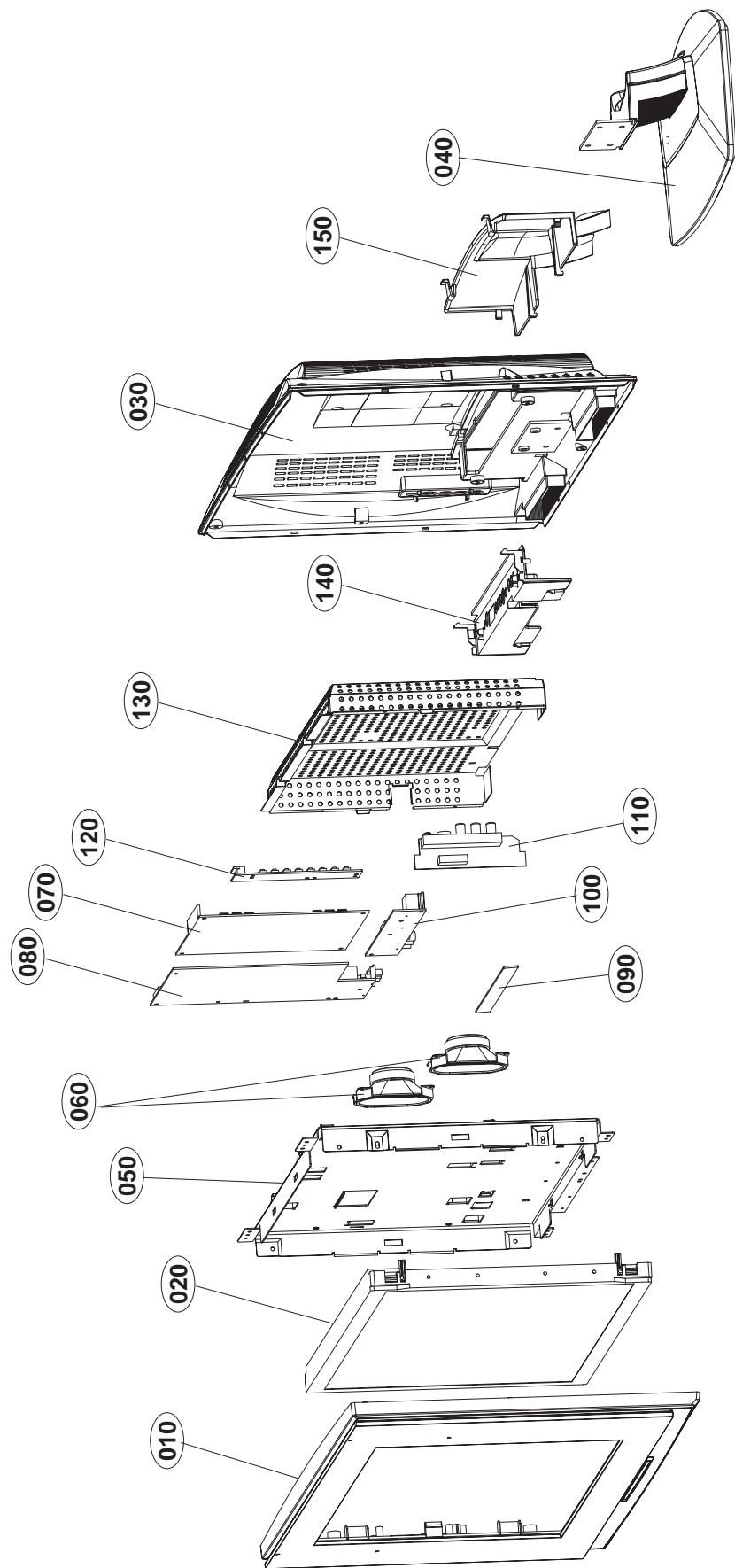
The PWM Step-Up DC/DC Converter circuit is used to generate the 33V used for the tuner.

15V power is directly used by the sound amplifier IC and is also used to generate 5V power through the regulator. 12V power is used for the LCD panel power, and 5V power is converted to 3.3V and 1.8V power through the regulator, which in turn supplies electrical power for ICs such as VCTI and scaler.

WIRING DIAGRAM



EXPLODED VIEW

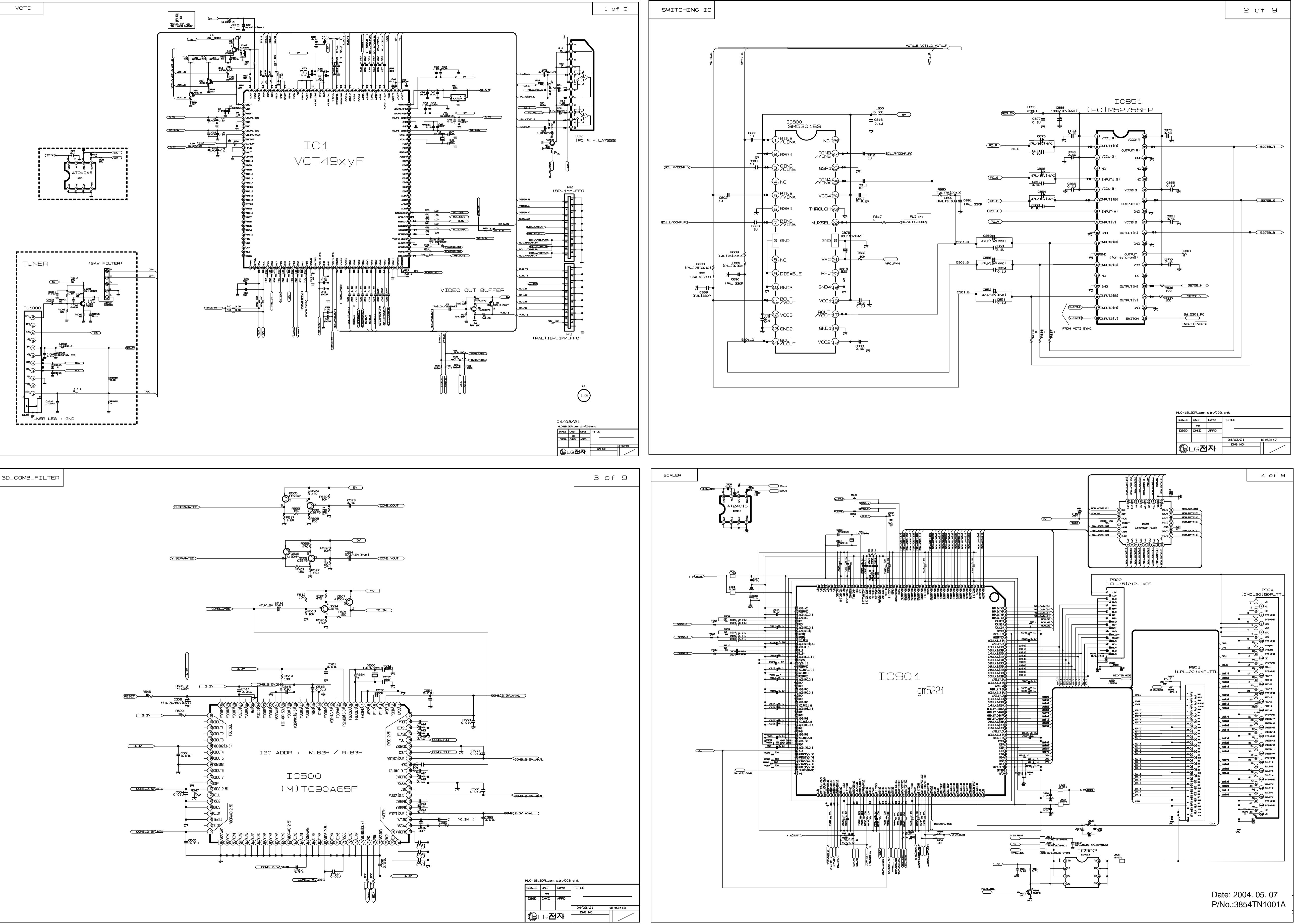


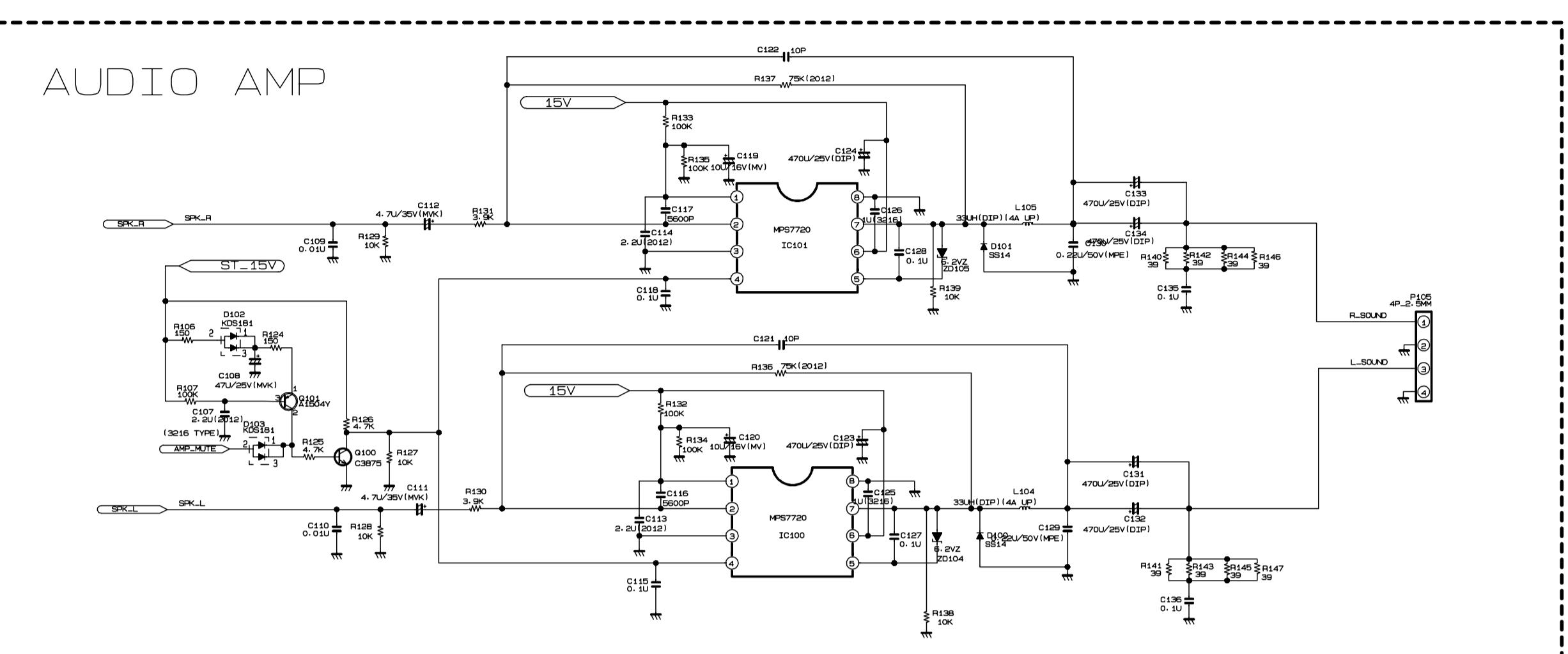
EXPLODED VIEW PARTS LIST

No.	PART NO.	DESCRIPTION
010	3091TKC146A	CABINET ASSEMBLY, 17LX1 BRAND 3090TKC106 NON
	3091TKC146B	CABINET ASSEMBLY, 17LX1R BRAND 3090TKC106 C/SKD
020	6304FLP213ALCD	LCD(LIQUID CRYSTAL DISPLAY), LC171W03-A4KJ LG PHILIPS TFT COLOR LEAD FREE(TV)
	or 6306V17001B	LCD(LIQUID CRYSTAL DISPLAY), LC171W03-A4K4 LG PHILIPS TFT COLOR
	or 6304FLP140B	LCD(LIQUID CRYSTAL DISPLAY),LC171W03-A4K7 LG PHILIPS TFT COLOR 17.1W,SS D-IC,IMAGE STICKING IMPROVEMENT,450NITS,25MS,6LAMP COST C
030	3809TKC061S	BACK COVER ASSEMBLY, 17LX1R 3808TKC051 ML-041B
	3809TKC061T	BACK COVER ASSEMBLY, 17LX1R 3808TKC051 ML-041B C/SKD
040	3043TKK179G	TILT SWIVEL ASSEMBLY, 17LX1R NON NOBLE BLACK(NO PRINT)
	3043TKK179H	TILT SWIVEL ASSEMBLY, 17LX1R NON NOBLE BLACK C/SKD(NO PRINT)
050	4951TKS154D	METAL ASSEMBLY, FRAME ML-041B 17LX1
	4951TKS154E	METAL ASSEMBLY, FRAME ML-041B 17LX1 C/SKD
060	6400GKTX01C	SPEAKER,FULLRANGE, F1527C-6428-4 K-TONE FULL-RANGE(GENERAL) 4 OHM 7/12W 85DB OTHERS 40*70MM TRACK TYPE
070	6871TPT280L	PWB(PCB) ASSEMBLY,POWER, RZ-17LA60 POWER TOTAL LIEN CHANG LIPS FOR LPL 17 WIDE PB FREE
	or 6871TPT280C	PWB(PCB) ASSEMBLY,POWER, 17RZ40 POWER TOTAL LIEN CHANG LIPS FOR LPL 17" WIDE
080	3313TN1033A	MAIN TOTAL ASSEMBLY, 17LX1R-UA MAIN BOARD BRAND (ML-041B) LF
090	6871TSTA04A	PWB(PCB) ASSEMBLY,SUB, 17LX1 IR BOARD LED & P/SW TOTAL BRAND (ML-041B) LF
100	6871TST964A	PWB(PCB) ASSEMBLY,SUB, RM/RT-15,17,20 DVD JACK BOARD VIDEO TOTAL BRAND ML-041B LF
110	6871TST995A	PWB(PCB) ASSEMBLY,SUB, 17LX1R SIDE A/V SUB TOTAL BRAND (ML-041B) LF
120	6871TST976B	PWB(PCB) ASSEMBLY,SUB, 17LX1R-UA CONTROL TOTAL BRAND (MAIN ML-041B) LF
130	4951TKK173C	METAL ASSEMBLY, REAR SHIELD ML-041B RZ-17LZ50 EMI-SPONGE
	4951TKK173D	METAL ASSEMBLY, REAR SHIELD ML-041B RZ-17LZ50 EMI-SPONGE C/SKD
140	3551TKK529G	COVER ASSEMBLY, 17LX1R REAR A/V ASSY ML-041B 1
150	3550TKK543B	COVER, 17LX1R REAR AV

DATE: 2005. 03. 04.				
*S	*AL	LOC. NO.	PART NO.	DESCRIPTION / SPECIFICATION
		ZD104	ODZ620009HB	UDZ S 6.2B TP ROHM SOD323 20
		ZD105	ODZ620009HB	UDZ S 6.2B TP ROHM SOD323 20
		ZD200	ODZ510009EE	UDZ S 5.1B TP ROHM-K SOD323
		ZD209	ODZ510009EE	UDZ S 5.1B TP ROHM-K SOD323
		ZD201	ODZ510009EE	UDZ S 5.1B TP ROHM-K SOD323
		ZD202	ODZ510009EE	UDZ S 5.1B TP ROHM-K SOD323
		ZD203	ODZ510009EE	UDZ S 5.1B TP ROHM-K SOD323
		ZD204	ODZ510009EE	UDZ S 5.1B TP ROHM-K SOD323
		ZD205	ODZ510009EE	UDZ S 5.1B TP ROHM-K SOD323
		ZD206	ODZ510009EE	UDZ S 5.1B TP ROHM-K SOD323
		ZD211	ODZ510009EE	UDZ S 5.1B TP ROHM-K SOD323
		D1151	ODZ330009DF	MTZJ33B TP ROHM-K DO34 0.5W
IC				
		IC905	OIZZTSA053A	ML-041B WXGA 17LX1R ATMEL 32
		IC3	OIKE702700D	"KIA7027AF 3, SOT-89 TP RESET"
		IC2	OISA722200A	LA7222 (1280 AUDIO) - - -
		IC200	OIMMRSG036A	"M24C02-WMN6T(P),LF SGS-THOMS"
		IC4	OIMCRAL006A	AT24C16AN-10SI-2.7 ATMEL 8P
		IC903	OIMCRAL006A	AT24C16AN-10SI-2.7 ATMEL 8P
		IC100	OIMCRMZ002A	MP7720 MONOLITHIC POWER SYST
		IC101	OIMCRMZ002A	MP7720 MONOLITHIC POWER SYST
		IC851	OIMCRM006A	"M52758FP MITSUBISHI 36PIN, R"
		IC1	OIPRPMN003C	VCT49XYF C7(NTSC+PAL) MICRON
		IC800	OIPRPNP001A	"SM5301BS(ATSC DTV) NPC 28P,H"
		IC901	OIPRPGN015C	"GM2221-BC-LF,PB FREE GENESIS"
		IC1101	OIPMGFA061A	"FAN1587AD33X FAIRCHILD 3P,DP"
		IC1103	OIPMGSG018D	"LD1086DT18TR SGS-THOMSON 3P,"
		IC1108	OIMCRKE010A	KIA7812AF KEC 2P DPACK R/TP
		IC1110	OIPMG00003A	"KIA78M08F KEC 3P,DPAK R/TP 8"
		IC1111	OIPMG00004A	"KIA7805AF KEC 3P,DPAK R/TP 5"
		IC1112	OIMCRKE010A	KIA7812AF KEC 2P DPACK R/TP
		IC1113	OIPMG00003A	"KIA78M08F KEC 3P,DPAK R/TP 8"
		IC1105	OIPMGFA061A	"FAN1587AD33X FAIRCHILD 3P,DP"
		IC1106	OIPMGSG018D	"LD1086DT18TR SGS-THOMSON 3P,"
		IC1114	OIPMGFA061A	"FAN1587AD33X FAIRCHILD 3P,DP"
		IC1115	OIPMGFA061A	"FAN1587AD33X FAIRCHILD 3P,DP"
		IC202	OISTL00026A	"MC14066BDR2G,LF ON SEMI 14P,"
COIL & CORE & INDUCTOR & FILTER				
		L104	6140TBZ045A	"38.5UH(DIP), 6A, P7.5, DR8.3"
		L105	6140TBZ045A	"38.5UH(DIP), 6A, P7.5, DR8.3"
		L1150	150-985B	DR8*11 2.4MH 0.16MM 270.5T
		L1100	6210TCE001G	HH-1M3216-501 CERATEC 3216MM
		L1101	6210TCE001G	HH-1M3216-501 CERATEC 3216MM
		L1103	6210TCE001A	HB-1S2012-080JT CERATEC 2012
		L1105	6210TCE001G	HH-1M3216-501 CERATEC 3216MM
		L1106	6210TCE001G	HH-1M3216-501 CERATEC 3216MM
		L1107	6210TCE001G	HH-1M3216-501 CERATEC 3216MM
		L200	6210TCE001A	HB-1S2012-080JT CERATEC 2012
		L201	6210TCE001A	HB-1S2012-080JT CERATEC 2012
		L202	6210TCE001A	HB-1S2012-080JT CERATEC 2012
		L203	6210TCE001A	HB-1S2012-080JT CERATEC 2012
		L204	6210TCE001G	HH-1M3216-501 CERATEC 3216MM
		L206	6210TCE001G	HH-1M3216-501 CERATEC 3216MM
		L853	6210TCE001G	HH-1M3216-501 CERATEC 3216MM
		L900	6210TCE001G	HH-1M3216-501 CERATEC 3216MM
		L901	6210TCE001G	HH-1M3216-501 CERATEC 3216MM
		L902	6210TCE001G	HH-1M3216-501 CERATEC 3216MM
		L903	6210TCE001G	HH-1M3216-501 CERATEC 3216MM
DATE: 2005. 03. 04.				
*S	*AL	LOC. NO.	PART NO.	DESCRIPTION / SPECIFICATION
		L905	6210TCE001A	HB-1S2012-080JT CERATEC 2012
		L1102	6210TCE001G	HH-1M3216-501 CERATEC 3216MM
		L205	6210TCE001A	HB-1S2012-080JT CERATEC 2012
		L800	6210TCE001G	HH-1M3216-501 CERATEC 3216MM
		L906	6210TCE001G	HH-1M3216-501 CERATEC 3216MM
		L908	6210TCE001G	HH-1M3216-501 CERATEC 3216MM
		Z1000	6200QL3002F	"X6966M EPCOS ST SIP5K, 6200Q"
		L10	OLC1032101A	10UH 10% 3216 R/TC FI-C3216-
		L1001	OLC1020101A	1UH 10% 2012 R/TC FI-B2012-1
		L1002	OLC1032101A	10UH 10% 3216 R/TC FI-C3216-
		L15	OLC1032101A	10UH 10% 3216 R/TC FI-C3216-
		L2	OLC1032101A	10UH 10% 3216 R/TC FI-C3216-
		L8	OLC1032101A	10UH 10% 3216 R/TC FI-C3216-
FET & TRANSISTOR				
		IC902	OTF492509AA	SI4925DY TP TEMIC 30V 6.1A
		IC1107	OTF492509AA	SI4925DY TP TEMIC 30V 6.1A
		Q1150	OTR322809AB	KTC3228-Y(KTC2383) TP KEC TO
		Q1	OTR387500AA	CHIP 2SC3875S(ALY) BK KEC -
		Q603	OTR387500AA	CHIP 2SC3875S(ALY) BK KEC -
		Q900	OTR387500AA	CHIP 2SC3875S(ALY) BK KEC -
		Q100	OTR387500AA	CHIP 2SC3875S(ALY) BK KEC -
		Q1000	OTR388109AA	KTC3881 CHIP TP KEC - -
		Q101	OTR150400BA	CHIP 2SA1504S(ASY) BK KEC -
		Q1100	OTR387500AA	CHIP 2SC3875S(ALY) BK KEC -
		Q1151	OTR387500AA	CHIP 2SC3875S(ALY) BK KEC -
		Q12	OTR150400BA	CHIP 2SA1504S(ASY) BK KEC -
		Q13	OTR150400BA	CHIP 2SA1504S(ASY) BK KEC -
		Q14	OTR150400BA	CHIP 2SA1504S(ASY) BK KEC -
		Q15	OTR387500AA	CHIP 2SC3875S(ALY) BK KEC -
		IC1104	OTFVI80005A	VISHAY SI4963DY R/TP SO-8 - 2
RESISTORs				
		C250	ORH1802D622	18K 1/10W 5 D.R/TP
		C251	ORH1802D622	18K 1/10W 5 D.R/TP
		L1104	ORH2202D622	22K 1/10W 5 D.R/TP
		R1004	ORH3000D622	300 1/10W 5 D.R/TP
		R1010	ORH7501D622	7.5K 1/10W 5 D.R/TP
		R1012	ORH7502D622	75K 1/10W 5 D.R/TP
		R106	ORH1500D622	150 1/10W 5 D.R/TP
		R107	ORH1003D622	100K 1/10W 5 D.R/TP
		R1108	ORH1003D622	100K 1/10W 5 D.R/TP
		R1109	ORH1003D622	100K 1/10W 5 D.R/TP
		R1151	ORH4700D622	470 1/10W 5 D.R/TP
		R1153	ORH1000D622	100 1/10W 5 D.R/TP
		R126	ORH4701D622	4.7K 1/10W 5 D.R/TP
		R132	ORH1003D622	100K 1/10W 5 D.R/TP
		R133	ORH1003D622	100K 1/10W 5 D.R/TP
		R134	ORH1003D622	100K 1/10W 5 D.R/TP
		R135	ORH1003D622	100K 1/10W 5 D.R/TP
		R14	ORH4701D622	4.7K 1/10W 5 D.R/TP
		R140	ORH0392D622	39 1/10W 5 D.R/TP
		R141	ORH0392D622	39 1/10W 5 D.R/TP
		R142	ORH0392D622	39 1/10W 5 D.R/TP
		R143	ORH0392D622	39 1/10W 5 D.R/TP
		R144	ORH0392D622	39 1/10W 5 D.R/TP
		R145	ORH0392D622	39 1/10W 5 D.R/TP
		R146	ORH0392D622	39 1/10W 5 D.R/TP
		R147	ORH0392D622	39 1/10W 5 D.R/TP
		R211	ORH0752D622	75 1/10W 5 D.R/TP

DATE: 2005. 03. 04.				
*S	*AL	LOC. NO.	PART NO.	DESCRIPTION / SPECIFICATION
		R2306	0RH4703D622	470K 1/10W 5 D.R/TP
		R2308	0RH5101D622	5.1K 1/10W 5 D.R/TP
		R2309	0RH5101D622	5.1K 1/10W 5 D.R/TP
		R2310	0RH0752D622	75 1/10W 5 D.R/TP
		ZD2306	0DZ620009HB	UDZ S 6.2B TP ROHM SOD323 20
IR BOARD				
		C2101	0CH3104K566	0.1UF 50V 10% X7R 2012 R/TP
		C3101	0CH3104K566	0.1UF 50V 10% X7R 2012 R/TP
		C3102	0CH3104K566	0.1UF 50V 10% X7R 2012 R/TP
		C3103	0CH3104K566	0.1UF 50V 10% X7R 2012 R/TP
		C3104	0CH3104K566	0.1UF 50V 10% X7R 2012 R/TP
		C3105	0CH3104K566	0.1UF 50V 10% X7R 2012 R/TP
		C3106	0CH3104K566	0.1UF 50V 10% X7R 2012 R/TP
		C3107	0CH3104K566	0.1UF 50V 10% X7R 2012 R/TP
		L2101	6210TCE001A	HB-1S2012-080JT CERATEC 2012
		L3300	6210TCE001G	HH-1M3216-501 CERATEC 3216MM
		Q2101	0TR387500AA	CHIP 2SC3875S(ALY) BK KEC -
		Q2102	0TR387500AA	CHIP 2SC3875S(ALY) BK KEC -
		Q2103	0TR387500AA	CHIP 2SC3875S(ALY) BK KEC -
		Q3101	0TR387500AA	CHIP 2SC3875S(ALY) BK KEC -
		Q3102	0TR387500AA	CHIP 2SC3875S(ALY) BK KEC -
		Q3103	0TR387500AA	CHIP 2SC3875S(ALY) BK KEC -
		Q3104	0TR387500AA	CHIP 2SC3875S(ALY) BK KEC -
		Q3105	0TR387500AA	CHIP 2SC3875S(ALY) BK KEC -
		Q3106	0TR387500AA	CHIP 2SC3875S(ALY) BK KEC -
		Q3107	0TR387500AA	CHIP 2SC3875S(ALY) BK KEC -
		Q3108	0TR387500AA	CHIP 2SC3875S(ALY) BK KEC -
		R2101	0RH1000D622	100 1/10W 5 D.R/TP
		R2102	0RH1000D622	100 1/10W 5 D.R/TP
		R2103	0RH1001D622	1K OHM 1 / 10 W 2012 5.00% D
		R2104	0RH1001D622	1K OHM 1 / 10 W 2012 5.00% D
		R2105	0RH1001D622	1K OHM 1 / 10 W 2012 5.00% D
		R2106	0RH1000D622	100 1/10W 5 D.R/TP
		R3101	0RH2200D622	220 1/10W 5 D.R/TP
		R3102	0RH2200D622	220 1/10W 5 D.R/TP
		R3103	0RH2200D622	220 1/10W 5 D.R/TP
		R3104	0RH2200D622	220 1/10W 5 D.R/TP
		R3105	0RH2200D622	220 1/10W 5 D.R/TP
		R3106	0RH2200D622	220 1/10W 5 D.R/TP
		R3107	0RH2200D622	220 1/10W 5 D.R/TP
		R3120	0RH1001D622	1K OHM 1 / 10 W 2012 5.00% D
		R3211	0RH1000D622	100 1/10W 5 D.R/TP
		R3212	0RH1000D622	100 1/10W 5 D.R/TP
		R3213	0RH1000D622	100 1/10W 5 D.R/TP
		R3214	0RH1000D622	100 1/10W 5 D.R/TP
		R3215	0RH1000D622	100 1/10W 5 D.R/TP
		R3216	0RH1000D622	100 1/10W 5 D.R/TP
		R3217	0RH1000D622	100 1/10W 5 D.R/TP
		R3218	0RH0000D622	0 OHM 1 / 10 W 2012 5.00% D
		LED2100	0DL200000CA	SAM5670(DL-2LRG) BK Y-GREEN
		PA2101	6726TV0001A	TSOP4838SO1 VISHAY 38.0KHZ L
		LED801	0DLBE0158AA	BRIGHT LED ELECTRONICS BL-HB
		LED802	0DLBE0158AA	BRIGHT LED ELECTRONICS BL-HB
		LED803	0DLBE0158AA	BRIGHT LED ELECTRONICS BL-HB
		LED804	0DLBE0158AA	BRIGHT LED ELECTRONICS BL-HB
		LED805	0DLBE0158AA	BRIGHT LED ELECTRONICS BL-HB
		LED806	0DLBE0158AA	BRIGHT LED ELECTRONICS BL-HB
		LED807	0DLBE0158AA	BRIGHT LED ELECTRONICS BL-HB

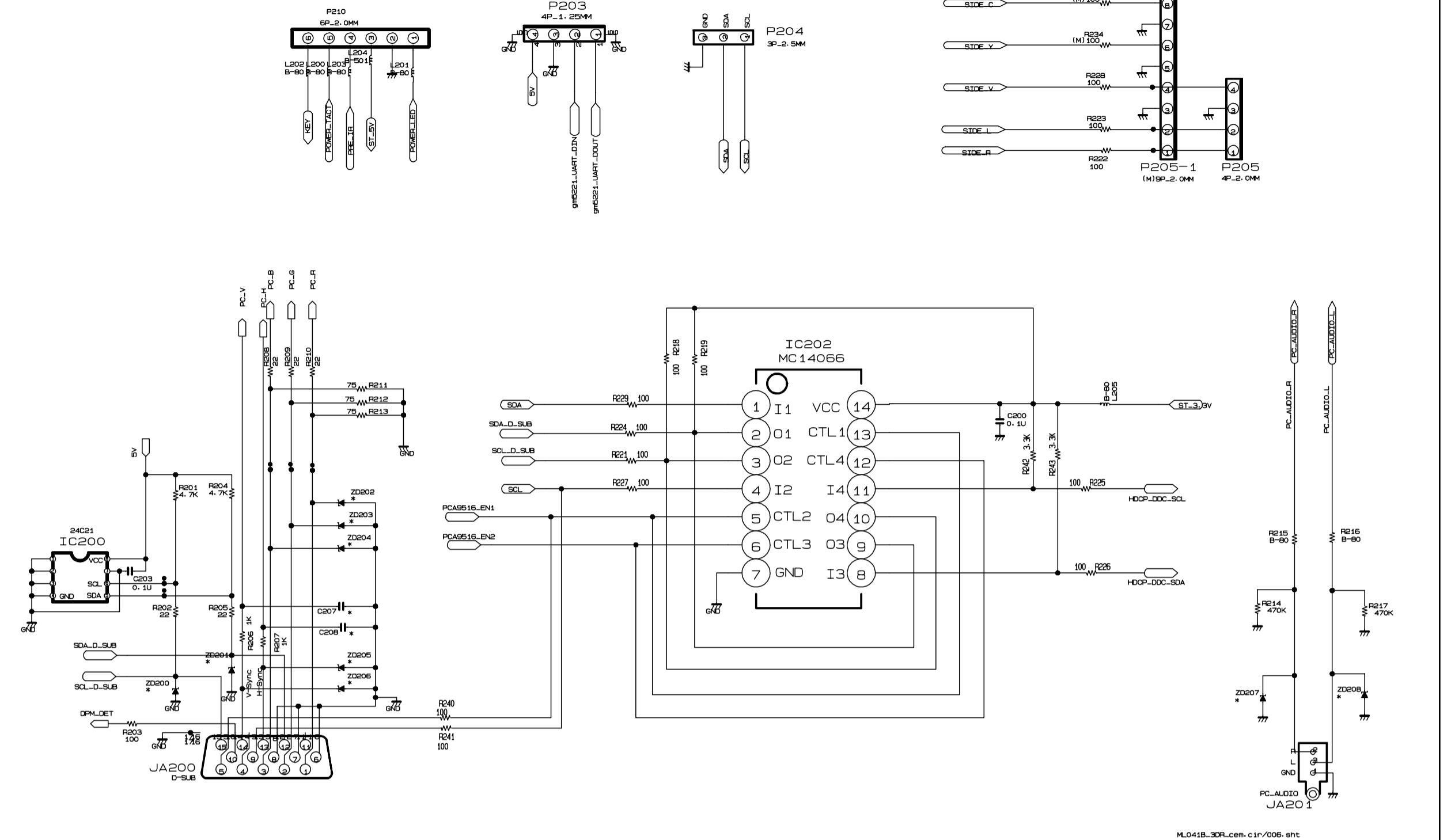




MJ.041B_30FLcem.cir/005.sch
SCALE: mm UNIT: Date: TITLE:
D560: CHD: APPRO: _____
04/03/21 18:53:21
DWG NO.: / /

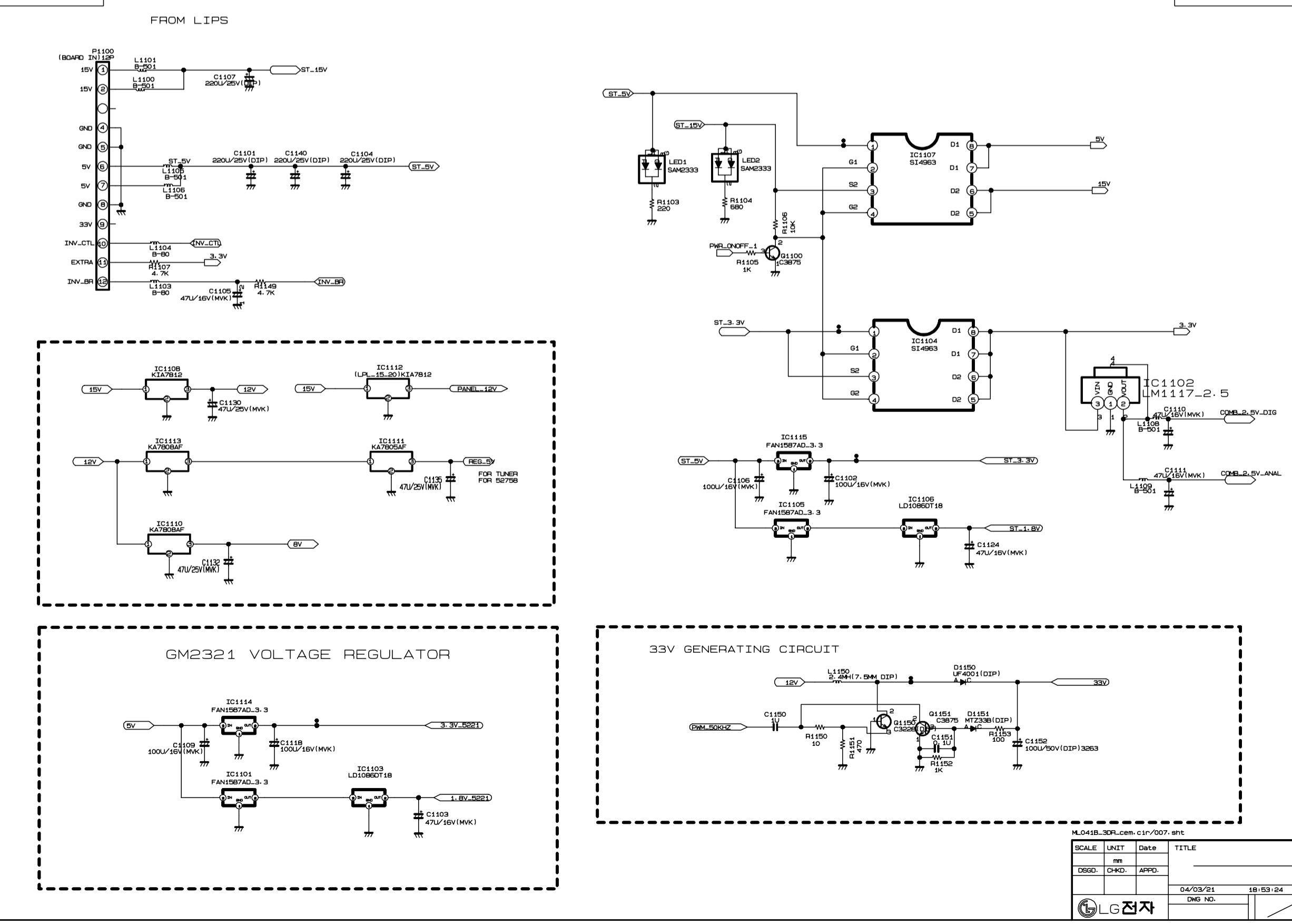
LG전자

FOR VISUAL_I2C

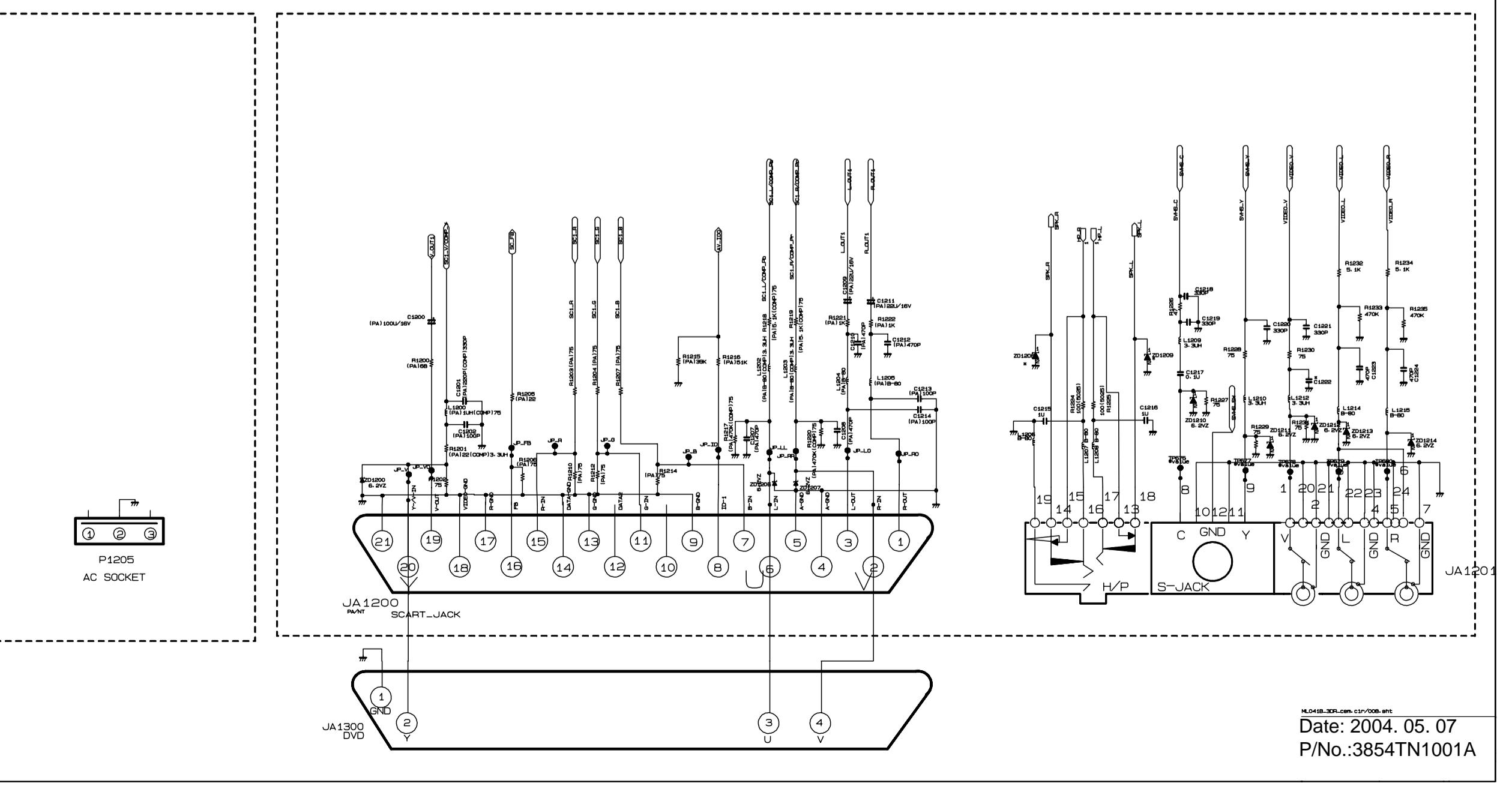


MJ.041B_30FLcem.cir/006.sch
SCALE: mm UNIT: Date: TITLE:
D560: CHD: APPRO: _____
04/03/21 18:53:23
DWG NO.: / /

LG전자



#AV BOARD#





P/NO : 3828TSL111D

Mar., 2005
Printed in Korea